

LEADER TIME SRL

PRODUCT SPECIFICATION

20*4 Characters COB LCD MODULE MODEL: LT-2004C-604 Ver:1.0

< >> Finally Specification

	CUSTOMER'S APPROVAL						
CUSTOMER:	CUSTOMER:						
SIGI	NATURE:	DATE:					

APPROVED	PM	PD	PREPARED
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Prepared By: LEADER TIME SRL VIA MONS. PROSDOCIMI, 27

36042 BREGANZE (VI)

I This specification is subject to change without notice. Please contact LT or it's representative before designing your product based on this specification.

Doc. No.:

Revision Status

Version	Revise Date	Page	Content	Modified By
VER 1.0	2010/5/24		First Issued	

Table of Contents

No. Contents Page	е
1. FEATURES4	
2. MECHANICAL SPECIFICATIONS4	
3. ELECTRICAL SPECIFICATIONS4	
4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM6	
5. TIMING CHARACTERISTICS7	
6. COMMAND LIST9	
7.CHARACTER GENERATOR ROM10	
8. QUALITY SPECIFICATIONS11	
9. RELIABILITY16	
10. HANDLING PRECAUTION17	
11. OUTLINE DIMENSION18	

Doc. No.:

1. FEATURES

The features of LCD are showed as follows

* Display mode : FSTN /Transflective/Positive

* Controller IC : ST7066U-0A(English and Japanese)

* Display format : 20X4Characters * Interface : 4 Bit or 8 Bit MPU * Driving Method : 1/16Duty, 1/5Bias

* Viewing Direction : 6 O'clock * Backlight : Side RGW

*Sample NO. : EC2004B1FSE6B-1.0/20100521

2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	146(W) x62.5(H) x13.6MAX(T)	mm
Viewing Area	123.5 (W) x 43(H)	mm
Activity Display Area	118.84(W)x38.47(H)	mm
Character Font	5x8 Dots	-
Character Size	4.84(W)x9.22(H)	mm
Character Pitch	6.00 (W) x9.75(H)	mm
Dot Size	0.92(W)x1.10(H)	mm

3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C)

Item	Symbol	Min	Max	Unit
Supply Voltage For Logic	Vdd	-0.3	7.0	V
Supply Voltage For LCD Drive	V_{LCD}	VDD-10	V _{DD} +0.3	V
Input Voltage	Vin	-0.3	V _{DD} +0.3	V
Operating Temp.	Тор	-20	+70	°C
Storage Temp.	Tst	-30	+80	°C

^{*.} NOTE: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

3-2 ELECTRICAL CHARACTERISTICS

Item	1	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Logic supply	Voltage	V _{DD} – V _{ss}		4.5	5	5.5	V
LCD Di	rive	V _{LCD}		4.2	4.5	4.8	V
Input Voltage	"H" Level	V _{IH}	Ta = 25 °C	0.7 Vdd	-	VDD	V
	"L" Level	V _{IL}	$V_{DD}=5V\pm10\%$	-0.3	-	0.6	V
Frame Free	quency	f _{FLM}		ı	84.7	-	Hz
Current Cons	sumption	I _{DD}		ı	1.9	-	mA

3-3 BACKLIGHT

3-3-1. Absolute Maximum Ratings

Item	Symbol	Symbol Condition		Min.			Тур.			Мах.		Unit
item	Cyllibol	Condition	R	G	W	R	G	W	R	G	W	Oilit
Forward Current	IF		1	-	-	40	60	60	60	80	60	mA
Reverse Voltage	VR	Ta = 25 °C	-	-	1	-	-	-	5	5	5	V
Power Dissipation	PD		-	-	-	-	-	-	132	256	192	mW

3-3-2. Electrical-optical Characteristics

5-3-2. Electrical-o	pucai Ci	iai acteristic	3													
lt a m	0	Min. Typ.			Max.											
Item	Symbol	Condition	R	G	٧	٧	R	G	٧	V	R	G	V	V	Unit	
Forward Voltage	lv	JED-40m A	-	-	-	-	2.2	3.3	3	.3	-	-		-	٧	
Emission wavelength		IFR=40mA IFG=60mA IFW=60mA Ta = 25 °C	620	515	X 0.25	Y 0.25	630	525	X 0.28	Y 0.28	640	535	X 0.31	Y 0.31	nm	
Average Luminous Intensity	Lv	1a - 25 C	20	100	16	60	-	-		-	-	-		-	cd/m ²	

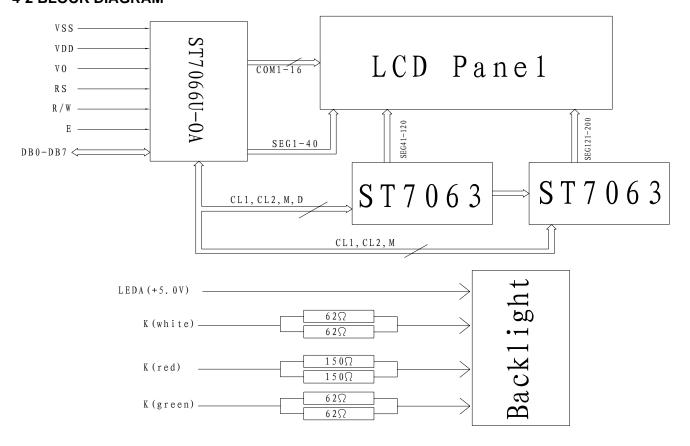
The brightness is measured without LCD panel

4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

4-1 INTERFACE PIN FUNCTION DESCRIPTION

PIN NO.	SYMBOL	FUNCIONS
1	VSS	Ground
2	VDD	Supply voltage for logical circuit
3	V0	Supply voltage for LCD driving
4	RS	A signal for selecting registers. 1: Data Register (for read and write)
4	KS	0: Instruction Register (for write)
5	R/W	A signal for selecting read or write actions.1: Read, 0: Write.
6	E	A enable signal for reading or writing data.
7-14	DB0~DB7	8 Bit Data Bus
15	LEDA	Backlight(+5V)
16	K(white)	Backlight(-)
17	K(red)	Backlight(-)
18	K(green)	Backlight(-)

4-2 BLOCK DIAGRAM



5. TIMING CHARACTERISTICS

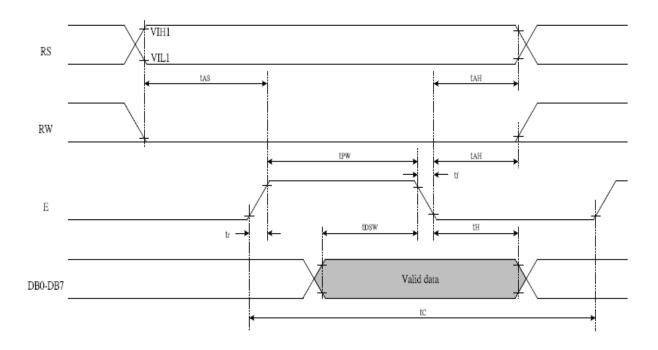
5-1 Write mode

T _C	Enable Cycle Time	Pin E	1200	-	-	ns
T_PW	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise/Fall Time	Pin E	-	-	25	ns
T _{AS}	Address Setup Time	Pins: RS,RW,E	0	-	-	ns
T _{AH}	Address Hold Time	Pins: RS,RW,E	10	•	-	ns
T _{DDR}	Data Setup Time	Pins: DB0 - DB7	-	-	100	ns
T _H	Data Hold Time	Pins: DB0 - DB7	10	1	-	ns

5-2 Read mode

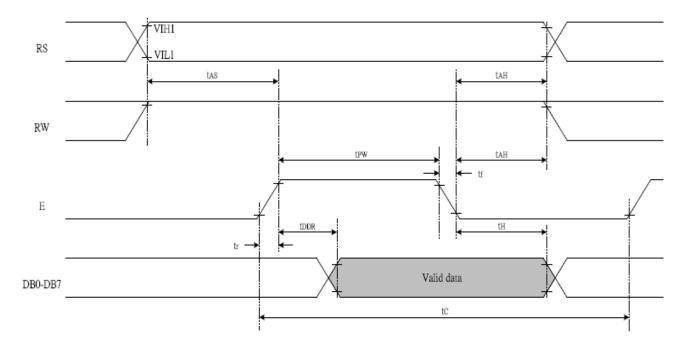
T _C	Enable Cycle Time	Pin E	1200	-	-	ns
T_PW	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise/Fall Time	Pin E	-	-	25	ns
T _{AS}	Address Setup Time	Pins: RS,RW,E	0	-	-	ns
T _{AH}	Address Hold Time	Pins: RS,RW,E	10	-	-	ns
T _{DDR}	Data Setup Time	Pins: DB0 - DB7	-	-	100	ns
T _H	Data Hold Time	Pins: DB0 - DB7	10	-	-	ns

5-3 Write timing mode diagram

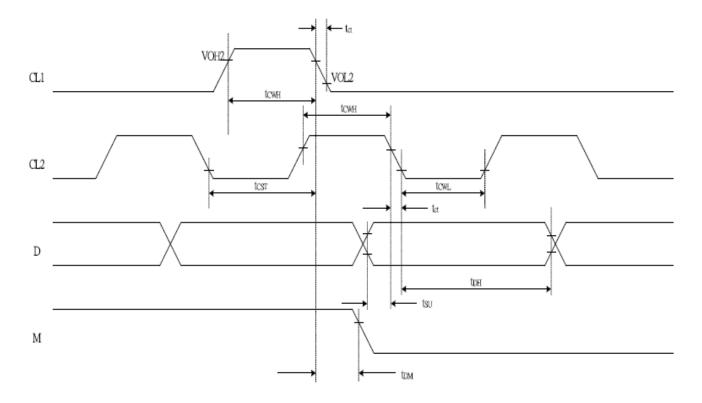


Doc. No.:

5.4 Read timing mode diagram



5-5 Interface timing mode



6. COMMAND LIST

6-1 Instruction Table

-1 mstruction	Instruction Code										Description		
Instruction	RS	R/W	DB7	DB6		DB4		DB2	DB1	DB0	Description	Time (270KHz)	
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from AC	1.52 ms	
Return Home	0	0	0	0	0	0	0	0	1	x	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.52 ms	
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	s	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	37 us	
Display ON/OFF	0	0	0	0	0	0	1	D	С	В	D=1:entire display on C=1:cursor on B=1:cursor position on	37 us	
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	х	x	Set cursor moving and display shift control bit, and the direction, without changing DDRAM data.	37 us	
Function Set	0	0	0	0	1	DL	N	F	x	х	DL:interface data is 8/4 bits N:number of line is 2/1 F:font size is 5x11/5x8	37 us	
Set CGRAM address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter	37 us	
Set DDRAM address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter	37 us	
Read Busy flag and address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0 us	
Write data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM)	37 us	
Read data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM)	37 us	

Note:

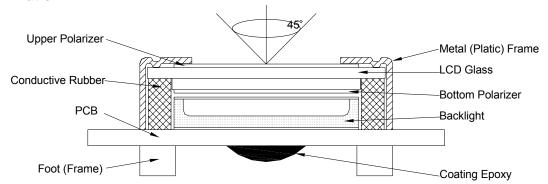
Be sure the ST7066U is not in the busy state (BF = 0) before sending an instruction from the MPU to the ST7066U. If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself. Refer to Instruction Table for the list of each instruction execution time.

7. CHARACTER GENERATOR ROM

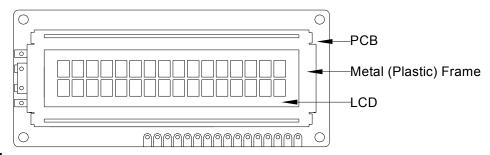
NO.7066-0A 67-64 0000 0001 0010 0011 0100 0101 0110 0111 1000 1001 1010 1011 1100 1101 | 1110 | 1111 **60-60** CG ij, Œ 0000 RAM (1)-0001 (2)ш ш ш 0010 (3)≅. .53 0011 (4)ŀ **(5)** 0.100 1 Ш ш (0)0101 6 (7)0410 W × П (8) 0.111 1000 (1)Ш ... (2)1001 ... I (3)1010 ш ж :::: Ħ (4)1011 ж (5). 1100 • M (6) 1101 m 1110 (7)ш (8)1111

8. QUALITY SPECIFICATIONS

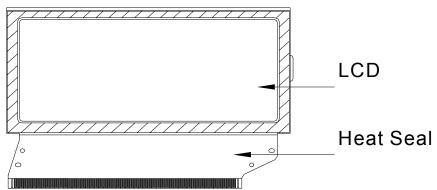
- 8 1. LCM Appearance and Electric inspection Condition
- 1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



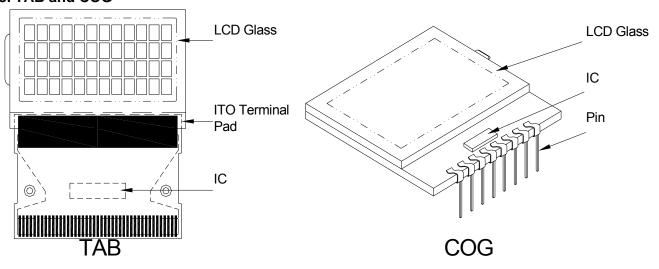
- 2. View Angle: with in 45° around perpendicular line.
- 8- 2. Definition
- 1. COB



2. Heat Seal



3. TAB and COG



Doc. No.:

8-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (||) ordinary single inspection is used.

2.Acceptance

Major defect: AQL = 0.25%Minor defect: AQL = 0.65%

8-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

2.SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing, extra, wrong component or wrong orientation		Reject
Minor	Component position shift component soldering pad	X < 3/4Z Y > 1/3D	Reject
Minor	Component tilt component soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component PAD ← PCB	θ <u><</u> 20°	Reject

3. Metal (Plastic) Frame

Defect	Inspection Item	lı	^r ds	
Major	Crack / breakage	Anywhere		Reject
		W	L	Acceptable of Scratch
		w<0.1mm	Any	Ignore
		0.1 <u><</u> w<0.2mm	L <u><</u> 5.0mm	2
Minor	Frame Scratch	0.2 <u><</u> w<0.3mm	L <u><</u> 3.0mm	1
		w <u>></u> 0.3mm	Any	0
		with distance gi	e to scratch lines e of frame (not	
				Acceptable of Dents / Pricks
		Ф <u><</u>	2	
	Frame Dent , Prick	1.0<4	1	
Minor	$\Phi = \frac{L + W}{2}$	1.5	0	
	2	Note: 1. Above criteria applicable to any two de / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (visible) can be ignored		
Minor	Frame Deformation	Exceed the dimension of drawing		
Minor	Metal Frame Oxidation		Any rust	

4. Flexible Film Connector (FFC)

Defect		ection Item	Inspection Standards			
Minor	-	d soldering	Within the angle +5°	Acceptable		
Minor	Uneven s	older joint /bump		Reject		
			Expose the conductive line	Reject		
Minor	Hole	$\Phi = \frac{L + W}{2}$	Φ > 1.0mm	Reject		
Minor	Position shift Y Alignment D Position shift		Y > 1/3D	Reject		
Minor		- - - - -	X > 1/2Z	Reject		

5. Screw

Defect	Inspection Item	Inspection Standards		
Major	Screw missing/loosen		Reject	
Minor	Screw oxidation	Any rust	Reject	
Minor	Screw deformation	Difficult to accept screw driver	Reject	

6. Heatseal 、TCP 、FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	Ф> 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift	Y > 1/3D	Reject
IVIIIOI	T X	X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

LED Backing Flotective Filli and Others						
Defect	Inspection Item	Inspection Standards				
		Acceptable number of units				
		Ф <u><</u> 0.10mm				
		0.10<Φ <u><</u> 0.15mm				
Minor	LED dirty, prick	0.15<Φ <u><</u> 0.2mm	1			
		Ф>0.2mm	0			
		The distance between any two spots should be ≥5mm Any spot/dot/void outside of viewing area is acceptable				
Minor	Protective film tilt	Not fully cover LCD Re				
Major	COG coating	Not fully cover ITO circuit Re				

8. Electric Inspection

Defect	efect Inspection Item Inspection Standards		
Major	Short		Reject
Major	Open		Reject

9. Inspection Specification of LCD

Defect	Insp	ect Item		Inspection Standards					
		* Glass Scratch	W	_	<u>0.03</u>	0.0	0.0 <u><</u> W>0.0	5 \	N>0.05
		* Polarizer Scratch	L				L<3		Any
Minor Linear Defect		* Fiber and Linear	ACC. NO.	1			1		Reject
		material	Note	L is the le	ngth and V	V is th	is the width of the defe		efect
		* Foreign material		Ф <u><</u> 0.1	0.1<Φ <u><</u> 0	.15	0.15<Ф <u><</u> 0	.2	Ф>0.2
	Black Spot and			3EA / 100mm ²	2		1		0
Minor	Polarizer Pricked	and glass * Polarizer hole or protuberance by external force	Note		Φ is the average diameter of the defect. Distance between two defects > 10mm.				
		* Unobvious	-	Ф <u><</u>	0.3	0.3	<Ф <u><</u> 0.5	0	.5<Ф
	White Spot	transparent foreign material between	NO.	3EA / 1	00mm ²		1		0
Minor	and Bubble in polarizer	glass and glass or glass and polarizer * Air protuberance between polarizer and glass	Note		verage dia between tv				
				Ф <u><</u> 0.10	0.10<Φ <u><</u>	0.20	0.20<Ф<	<u><</u> 0.25	Ф>0.25
		<u>w</u>	ACC. NO.	3EA / 100mm ²	2		1		0
Minor	Segment Defect	- W-		W is more than 1/2 segment width Reje				Reject	
	20.00.		Note	$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm					
			Ф	Φ <u><</u> 0.10	0.10<Ф<	0.20	0.20<Ф<	<u>0.25</u>	Ф>0.25
	Protuberant	w	W	Glue	W <u><</u> 1/2 × W≤0.		W <u><</u> 1/2 W <u><</u> 0		Ignore
Minor	Segment	$\Phi = (L + W)/2$	ACC. NO.	3EA / 100mm²	2		1		0
			1. Seg	ment	1		1		
			Е		<u><</u> 0.4mm		3 <u><</u> 1.0mm		1.0mm
Minor	Assembly		B-	A B-	-A<1/2B	B-	A<0.2	B-A	\<0.25
	Mis-alignment		Jud			Acc	Acceptable Acce		eptable
			2. Dot Matrix						
			Deformation>2°						Reject
Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft clot or a similar one. Otherwise, judged according to the above items: "Black spot" and "White Spot"						

9. RELIABILITY

NO.	Item	Condition	Criterion
1	High Temperature Operating	70℃, 96Hrs	
2	Low Temperature Operating	-20℃, 96Hrs	
3	High Humidity	60℃, 90%RH, 96Hrs	
4	High Temperature Storage	80℃, 96Hrs	
5	Low Temperature Storage	-30℃, 96Hrs	No defect in cosmetic and
		Random wave	operational function allowable.
6	Vibration	10 ~ 100Hz	Total current Consumption should be below double of initial value.
0	Vibration	Acceleration: 2g	
		2 Hrs per direction(X,Y,Z)	
		-20℃ to 25℃ to 70℃	
7	Thermal Shock	(60Min) (5Min) (60Min)	
		16Cycles	
8	ESD Testing	Contract Discharge Voltage: +1 ~ 5kV and –1 ~ –5kV	There will be discharged ten times at every discharging
	LOD Testing	Air Discharge Voltage: +1 ~ 8kV and –1 ~ -8kV	voltage cycle. The voltage gap is 1kV.

Note: 1) Above conditions are suitable for standard products.
2) For restrict products, the test conditions listed as above must be revised.

10. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers, which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Tricolor trifler thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water
- Kenton
- Aromatics

(3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

(4) Packaging

- Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
- To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.

(5) Caution for operation

- It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's .which will come back in the specified operating temperature range.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- -A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is required.

(6) Storage

In the case of storing for a long period of time, (For years) for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)

(7) Safety

- It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol. Which should be burned up later. When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

Issued Date: 2010.5.24 Doc. No.: 11. OUTLINE DIMENSION A B \mathcal{C} Q APPROVED Outline 082 ∞ <u>B</u> DOTS SIZE -0.98 5:1 080 -4.84-LEDA REVISION RECORD 9 I. 10 — First Issue - 91 ·I 2010, 04, 20 R∕ M **DB7** 2 DRAWN - 6. 22 - 67 .6 -**DB6** S 085 9 BYCK 00/ DB4 DB3 **NSS** FRONT CONNECTION CONNECTION M PIN e 22. 20 ∓0. 3 (45, 80) (7, 35) VIEWING DIRECTION -2.50 123. 50 (V. A) ±0. 1 -134. 20±0. 2- -146.00 ± 0.3 142.48±0.2-7-18-@1.0 -(118.84 A.A)-- P2. $54x17=43.18\pm0.1$ - 16. 24 ± 0.1 2.54 (13.58) -(13.015)67.01-9Z.∱-- 22' 00 ∓ 0' 3 --- 62.50±02.3 В